ICKEM2018 - Hierarchically Structured Materials (HSM)

Message from the Guest Editor

Dear Colleagues,

The 8th International Conference on Key Engineering Materials (ICKEM 2018) (http://www.ickem.org/) will be held, 16 – 18 March, 2018, at the Osaka International Convention Center, Osaka, Japan.

The purpose of the 8th International Conference on Key Engineering Materials is to bring together researchers, engineers and practitioners interested in the whole range of fields related to the materials. Papers presenting original works are invited on the topics listed below.

- Biomaterials in Different Applications
- Novel Composite Materials in Vivid Applications
- Application of Novel Materials in Civil Engineering
- Advances in Materials and Manufacturing Technology
- Materials and Technologies in Environmental Engineering
- Studies on Corrosion, Coating, and Aspects of Chemical Engineering
- Electrical, Electronic, and Optoelectronic Materials: Synthesis and Applications
- Trends in the Development of Nanomaterials, Nanocomposites and Nanotechnology

We invite researchers to submit their contributions to this Special Issue.
Prof. Alexander K

mdpi.com/si/12139
Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High visibility:** indexed by the Science Citation Index Expanded (Web of Science), Ei Compendex and other databases. Citations available in PubMed, full-text archived in PubMed Central.

**CiteScore** (2018 Scopus data): 3.26, which equals rank 97/439 (Q1) in 'General Materials Science'.

Contact Us

*Materials*

MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
Fax: +41 61 302 89 18
www.mdpi.com

materials@mdpi.com

@Materials_Mdpi